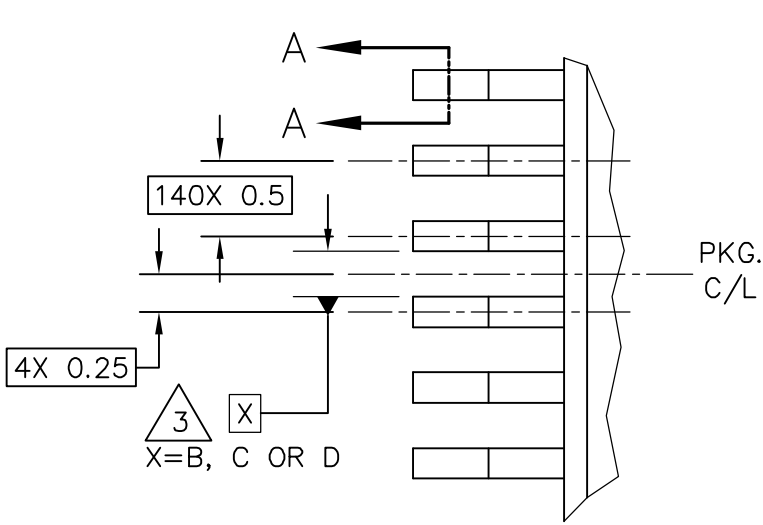
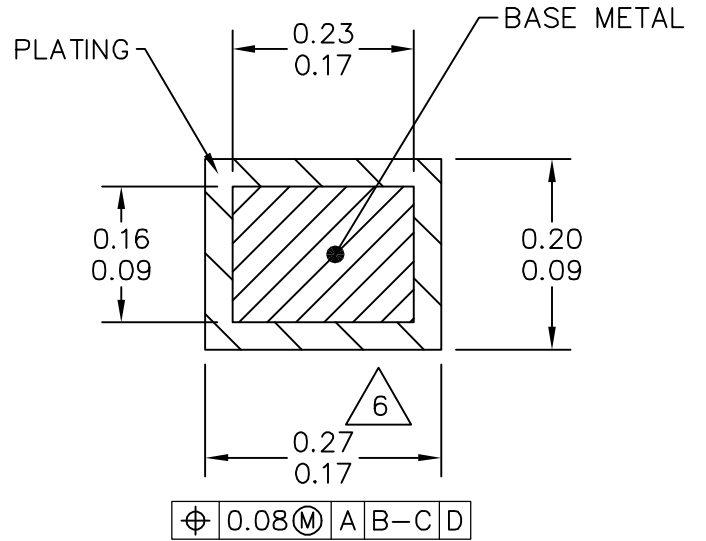


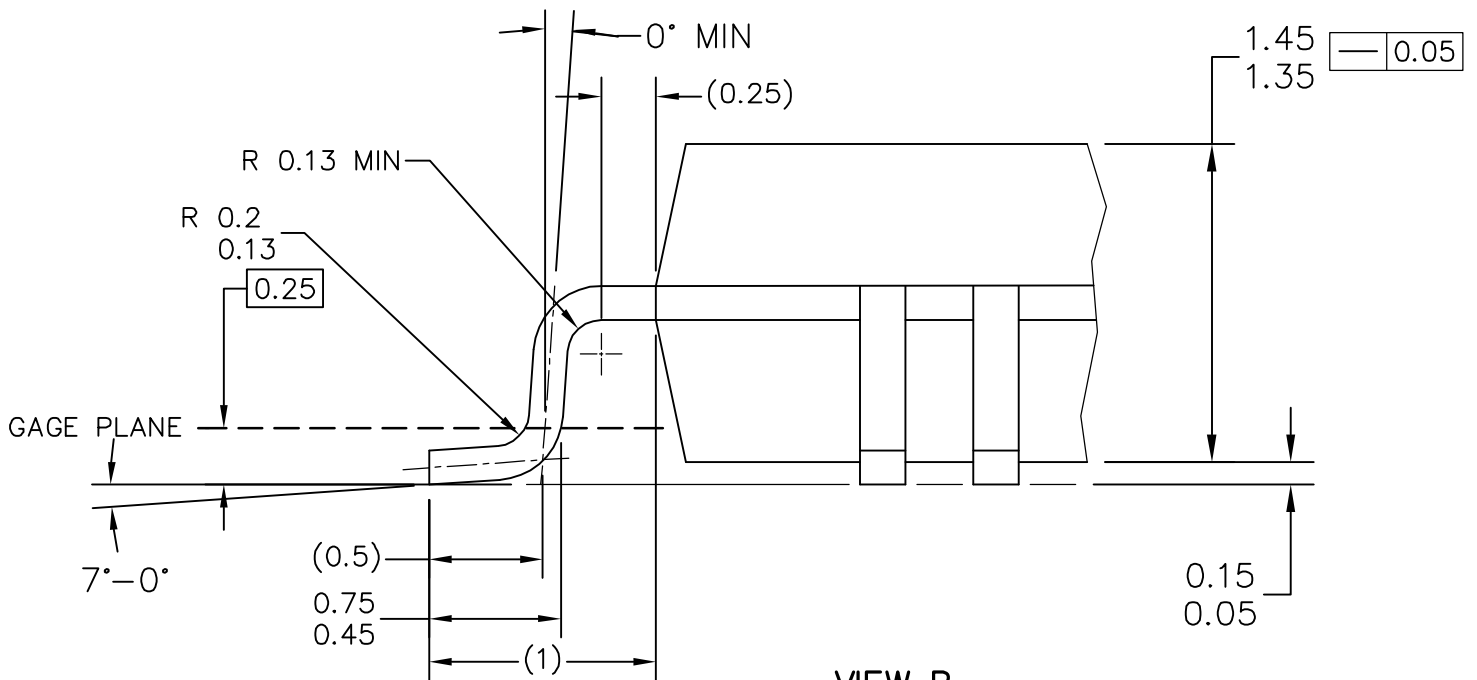
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TITLE: LQFP, 20 X 20 X 1.4 PKG, 0.5 MM PITCH, 144 I/O	DOCUMENT NO: 98ASS23177W	REV: J
	STANDARD: NON-JEDEC	
	SOT486-2	25 JAN 2016



VIEW A



SECTION A-A
ROTATED 90° CW
144 PLACES



VIEW B

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	STANDARD: NON-JEDEC	
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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUMS B, C AND D TO BE DETERMINED AT DATUM PLANE H.
4. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY A MAXIMUM OF 0.1 mm.
5. THIS DIMENSIONS DO NOT INCLUDE MOLD PROTRUSIONS. THE MAXIMUM ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. THIS DIMENSIONS ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
6. THIS DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION. PROTRUSIONS SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL BE 0.07 MM.
7. THIS DIMENSIONS ARE DETERMINED AT THE SEATING PLANE, DATUM A.

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